



International Electronics Manufacturing Initiative

IEEE/CPMT Participation in Roadmap



IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

Rolf Aschenbrenner
European Kick-Off Meeting



**IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY**

The IEEE Components, Packaging and Manufacturing Technology (CPMT) Society is an international forum for scientists and engineers.

CPMT Vision

The pre-eminent global component, microsystems packaging and manufacturing society, serving its global members by providing the latest worldwide technology advancements

- **Academia:**

- Create new knowledge
- Educate students

- **Industry:**

- Produce products using new knowledge & talent
- Create applied knowledge

- **Government:**

- Fund Basic infrastructure in science & engineering research and education

- **Distribute knowledge - latest technology advancements**
 - **4 *Transactions*, 30 conferences/workshops, Website**
 - **Chapter meetings, email, DL Lists**
- **Develop professional skills: Education, Training, Tutorials**
- **Life-long learning**



IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

- **General Packaging**
- **IC Packaging**
- **Electronics Manufacturing**
- **Materials**
- **Thermal**
- **Reliability**
- **Electrical Test**
- **VLSI Packaging**
- **Systems Packaging**
- **Opto, Photonics Packaging**
- **Power Packaging**
- **Electrical Design & Modeling**
- **MEMS & Microsystems Packaging**
- **Consumer Packaging**
- **Environmentally-Friendly Packaging**
- **Packaging Education**
- **Contacts (Holm)**
- **Nanopackaging**



IEEE COMPONENTS, PACKAGING AND
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TC-Nano Nano Packaging

Rao Tummala

TC-M Materials

Rajen Chanchani

TC-ASTR Accelerated Stress Testing and Reliability

Mark Gibbel

TC-Opto Fiber Optics & Photonics

Sue Law

TC-Test Electrical Tests

Bruce Kim

TC-EDMS Electrical Design, Modeling and Simulation

M. Swaminathan

TC-Therm Thermal Management

Tony Mak

TC-Ed Education

Rao Tummala

TC-ECCC Electrical Contacts, Connectors and Cables

Jerry Witter

TC-Assy IC and Packaging Assembly

M. Goetz

TC-HDSB High Density Substrates and Boards

Yoshitaka Fukuoka

TC-MEMS MEMS and Sensor Packaging

Erik Jung

TC-PEP Power Electronics Packaging

Douglas Hopkins

TC-RF+W RF and Wireless

Craig A. Gaw

TC-SP Systems Packaging

Erich Klink

TC-WLP Wafer Level Packaging

Michael Töpfer

TC-EM Electronics Manufacturing

Walter J. Trybula

TC-GEMP Green Electronics, Manufacturing and Packaging Hansjörg Griese

INEMI CPMT Participation In Technical Areas

NEMI Roadmap Committee Name	NEMI Roadmap Committee 2004 CPMT Members
Board Assembly	Dr. Dongkai Shangguan, Flextronics Dongkai.Shangguan@flextronics.com
Digital Silicon	Walter J. Trybula, International Sematech, Manufacturing TC Chair w.trybula@ieee.org
Display	Dr. Ephraim Suhir suhirE@aol.com
Electronic Connectors	Gerry Witter, Chugai USA Inc., Electrical Contacts TC Chair, g.witter@ieee.org
Energy Storage Systems	Douglas Hopkins, State University of New York at Buffalo, Power Electronics Packaging TC Chair d.hopkins@ieee.org
Environmentally Conscious Electronics	Hansjörg Griese, Fraunhofer Institute for Reliability and Microintegration, Green Electronics TC Chair griese@izm.fraunhofer.de

NEMI Roadmap Committee Name	NEMI Roadmap Committee 2004 CPMT Members
Modeling, Simulation and Design Tools	Walter J. Trybula, International Sematech, Manufacturing TC Chair w.trybula@ieee.org
Packaging	Erik Jung, Fraunhofer Institute for Reliability and Microintegration, MEMS and Sensor Packaging TC Chair erju@izm.fraunhofer.de
Passive Components	Leonard W. Schaper, University of Arkansas, Discrete and Integral Passives TC Chair schaper@uark.edu
Product Lifecycle Information Management	Walter J. Trybula, International Sematech, Manufacturing TC Chair w.trybula@ieee.org
RF-Components	Craig A. Gaw, Motorola Inc., RF and Wireless TC Chair c.a.gaw@ieee.org
Test, Inspection and Measurement	Bruce Kim, Center for Solid State Electronics Research, Electrical Test TC Chair Bruce.Kim@asu.edu
Thermal Management	Tony Mak, Dallas Semiconductor, Thermal/Thermomechanical TC Chair t.mak@ieee.org

Benefits for CPMT

1. Insight into „hot topics“ in industry
2. Better ability to define workshops and conferences

www.cpmt.org

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